

ABSTRACT

Provided are a hollow electronic device sealing resin sheet that can secure a hollow region of a hollow electronic device package and that can restrain the hollow electronic device package from being warped, and a hollow electronic device package. The resin sheet is a hollow electronic device sealing resin sheet including a first resin layer; and a second resin layer. The first and second resin layers each include a filler, and the resin sheet satisfies the following expressions (1) and (2): "content (% by volume) of the filler in the first resin layer" < "content (% by volume) of the filler in the second resin layer" (1); and "viscosity of the first resin layer" > "viscosity of the second resin layer" (2).